Technical Data Sheet

BERGQUIST GAP PAD TGP HC1000

Known as BERGQUIST GAP PAD HC1000
October 2018

PRODUCT DESCRIPTION

"Gel-Like" Modulus Gap Filling Material.

Technology	Silicone
Appearance	Gray
Reinforcement Carrier	Fiberglass
Thickness	0.254 to 0.508mm , ASTM D374
Inherent Surface Tack	2 (1 sided)
Application	Thermal management, TIM (Thermal Interface Material)
Operating Temperature Range	-60 to 200ºC

FEATURES AND BENEFITS

- Thermal Conductivity: 1.0 W/m-K
- Highly Conformable, low hardness
- "Gel-like" modulus
- Fiberglass reinforced for puncture, shear and tear resistance

BERGQUIST GAP PAD TGP HC1000 is an extremely conformable, low-modulus polymer that acts as a thermal interface and electrical insulator between electronic components and heat sinks. The "gel-like" modulus allows this material to fill air gaps to enhance the thermal performance of electronic systems.

BERGQUIST GAP PAD TGP HC1000 is offered with removable protective liners on both sides of the material.

TYPICAL APPLICATIONS

- Computer and peripherals
- Telecommunications
- Heat interfaces to frames, chassis or other heat spreading devices
- RDRAM™ memory modules / chip scale packages
- CDROM / DVD cooling
- Areas where irregular surfaces need to make a thermal interface to a heat sink
- DDR SDRAM memory modules
- FBDIMM modules

TYPICAL PROPERTIES OF CURED MATERIAL

Young's modulus is calculated using 0.01 in/min, step rate of strain with a sample size 0.79 inch² .

Physical Properties		
Hardness, Shore 00 , Thirty second delay value , ASTM D2240, Bulk rubber		25
Heat Capacity, ASTM E1269, J/g-K		1.0
Density, Bulk rubber, ASTM D792, g/cc		1.6
Flammability, UL 94		V-0
Young's Modulus, ASTM D575	kPa (psi)	275 (40)
Electrical Properties		
Dielectric Breakdown Voltage , ASTM D149, VAC		>5,000
Dielectric Constant, ASTM D150, 1,000Hz		5.5
Volume Resistivity, ASTM D257, ohm-meter		1×10^{11}
Thermal Properties		
Thermal Conductivity, ASTM D5470, W/(m-K)		1.0
Thermal Impedance, 0.020 inch ASTM D5470, ºC-in²/W:		
10% Deflection		1.3
20% Deflection		1.0
30% Deflection		0.96

The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

CONFIGURATIONS AVAILABLE

BERGQUIST GAP PAD TGP HC1000 is available in the following configurations:

- Sheet form
- Die-Cut parts
- Roll form

Natural tack both sides with fiberglass.

STORAGE

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 25ºC (±3), 50% RH (±10) for a 12 months shelf life. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
psi x 145 = N/mm²
MPa = N/mm²
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

Disclaimer

Note:
The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.
Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:
In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:
The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.
Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:
The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage: [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 1

This document was created and digitally signed by tdx.henkel.com at 2025-11-27T12:23:25.082Z